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In Re Application of: Radha Setty
S/N: 10/082,717
Entitled: DIRECTIONAL COUPLER
Filing Date: 05-26-2002

Art Unit: 2822
Examiner: Soward

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE
Letter Regarding Withdrawal of Claims

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03-17-04 / 967AG
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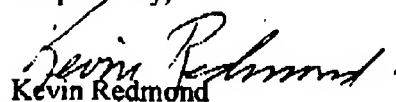
Sir:

Please find enclosed a copy of an Election and Response dated 07-28-03 indicating that claims 18-23 are to be withdrawn whereby "applicants reserve the right to submit a divisional application to the unelected invention of group two, claims 18-23 drawn to a process of making a product".

Also enclosed, please find Pages 8 and 9 of the Amendment and Response dated 12-10-03 whereby claims 18-23 are (previously withdrawn).

We now believe this application to be acceptable for continuance of examination and allowed for issue.

Respectfully,


Kevin Redmond
Attorney for the Applicant

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Signature Date of Signature

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In RE:
Serial no.: 10/082,717
Filing date: 02/26/2002
For: Low Cost Coupler
Inventor: Setty
Atty. Docket no.: 967AG
Group Art Unit: 2822
Examiner: Thomas

Mail Stop Non-Fee Amendment
Commissioner of Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Election and Response


Dear Sir:

This is in response to the Office Action dated 07/15/2003.

Restriction Requirement:

Applicants elect with traverse to prosecute the invention of group one, claims 1-17 and 24-35 drawn to a product.

Applicants reserve the right to submit a divisional application on the unelected invention of group two, claims 18-23 drawn to a process of making a product.



Respectfully submitted,



Kevin Redmond
Reg. No. 27,049

17. (original) The coupler according to claim 11 wherein the capacitor is formed by an electrode and a ground plane having a layer of the low temperature co-fired ceramic therebetween, the electrode and the ground plane each connected to a via.

18. (previously withdrawn) A method of manufacturing a coupler comprising the steps of:

- a) providing a plurality of layers of low temperature co-fired ceramic;
- b) punching a plurality of holes in the low temperature co-fired ceramic layers;
- c) filling the holes with a conductive material to form a plurality of vias;
- d) screening a plurality of circuit features onto the layers;
- e) stacking the layers;
- f) firing the stacked layers in an oven to form a unitary substrate; and
- g) attaching a transformer to the substrate.

19. (previously withdrawn) The method according to claim 18 wherein the circuit features are chosen from the group consisting of:

- a) resistors;
- b) capacitors;
- c) circuit lines;
- d) ground planes;
- e) terminals; and
- f) resistor overglaze.

20. (previously withdrawn) The method according to claim 18 wherein the transformer has a plurality of wire windings, the wire windings being welded to the terminals.
21. (previously withdrawn) The method according to claim 18 wherein the transformer is attached to the substrate using an adhesive.
22. (previously withdrawn) The method according to claim 18 wherein the transformer has a binocular core, the windings wound around the core so as to form an input port, a coupled port, an output port and a terminated port.
23. (previously withdrawn) The method according to claim 18 wherein the substrate is attached to a printed circuit board, further comprising the steps of:
- a) screening a solder paste onto a bottom surface terminal;
 - b) placing the substrate onto the printed circuit board; and
 - c) reflowing the solder paste such that the substrate is attached to the printed circuit board.